

P-Channel 30-V (D-S) MOSFET

PRODU	CT SUMMARY	1 1					
V _{DS} (V)	$R_{DS(on)}\left(\Omega\right)$	I _D (A) ^d	Q _g (Typ.)				
- 30	0.033 at V _{GS} = - 10 V	- 26	19 nC				
	0.046 at V _{GS} = -4.5 V	- 21	19110				

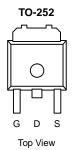
FEATURES

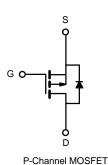
- Halogen-free
- TrenchFET® Power MOSFET
- 100 % R_g Tested
- 100 % UIS Tested



APPLICATIONS

- Load Switch
- · Notebook Adaptor Switch





Parameter	Symbol	Limit		
Drain-Source Voltage	V _{DS}	- 30	V	
Gate-Source Voltage	V _{GS}	± 20		
	T _C = 25 °C		- 26	
Continuous Drain Current (T _{.1} = 150 °C)	T _C = 70 °C	1 , 🗀	- 21	
Continuous Diain Current (1) = 130 °C)	T _A = 25 °C	l _D	- 12.9 ^{a, b}	
	T _A = 70 °C		- 9.6 ^{a, b}	^
Pulsed Drain Current	I _{DM}	- 112	A	
Continuous Course Danie Diada Current	T _C = 25 °C		- 4.1	
Continuous Source-Drain Diode Current	T _A = 25 °C	- Is	- 2.2 ^{a, b}	
Avalanche Current	1 0411	I _{AS}	- 20	
Single-Pulse Avalanche Energy	L = 0.1 mH	E _{AS}	20	mJ
	T _C = 25 °C		25	
Mariana Barra Biasinatian	T _C = 70 °C		20	10/
Maximum Power Dissipation	T _A = 25 °C	P _D	2.7 ^{a, b}	W
	T _A = 70 °C		1.7 ^{a, b}	
Operating Junction and Storage Temperature Rang	T _J , T _{stq}	- 55 to 150	°C	

THERMAL RESISTANCE RATINGS						
Parameter		Symbol	Typical	Maximum	Unit	
Maximum Junction-to-Ambient ^{a, c}	t ≤ 10 s	R _{thJA}	38	46	°C/W	
Maximum Junction-to-Foot	Steady State	R _{thJF}	20	25	5/88	

- a. Surface mounted on 1" x 1" FR4 board.
- c. Maximum under Steady State conditions is 85 °C/W. d. Based on T_C = 25 °C.



Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit
Static	- ,			-71		
Drain-Source Breakdown Voltage	V _{DS}	V _{GS} = 0 V, I _D = - 250 μA	- 30			V
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	AVpc/Ti		- 34		mV/
V _{GS(th)} Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	I _D = - 250 μA		5.3		°C
Gate-Source Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_{D} = -250 \mu\text{A}$	- 1.0		- 2.5	V
Gate-Source Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 25 \text{ V}$			± 100	nA
	I _{DSS}	V _{DS} = - 30 V, V _{GS} = 0 V			- 1	
Zero Gate Voltage Drain Current		V _{DS} = - 30 V, V _{GS} = 0 V, T _J = 55 °C			- 5	μA
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \ge -10 \text{ V}, V_{GS} = -10 \text{ V}$	- 30			Α
On State Diam Surem	_	V _{GS} = - 10 V, I _D = - 10 A			0.043	+
Drain-Source On-State Resistance ^a	R _{DS(on)}	V _{GS} = - 4.5 V, I _D = - 8 A		0.046	0.052	Ω
Forward Transconductance ^a	9 _{fs}	$V_{DS} = -10 \text{ V}, I_D = -10 \text{ A}$		28		S
Dynamic ^b	5.5					
Input Capacitance	C _{iss}			1350		
Output Capacitance	C _{oss}	V _{DS} = - 15 V, V _{GS} = 0 V, f = 1 MHz		255		pF
Reverse Transfer Capacitance	C _{rss}			190		
•		V _{DS} = - 15 V, V _{GS} = - 10 V, I _D = - 10 A		27	43	
Total Gate Charge	Q _g		19	25		
Gate-Source Charge	Q_{gs}	V _{DS} = - 15 V, V _{GS} = - 4.5 V, I _D = - 10 A		6		nC
Gate-Drain Charge	Q _{qd}			12		1
Gate Resistance	R _g	f = 1 MHz	0.5	2.2	4.4	Ω
Turn-On Delay Time	t _{d(on)}			13	25	
Rise Time	t _r	$V_{DD} = -15 \text{ V}, R_1 = 1.5 \Omega$		12	24	
Turn-Off DelayTime	t _{d(off)}	$I_D \cong -10 \text{ A}, V_{GEN} = -10 \text{ V}, R_q = 1 \Omega$		40	70	
Fall Time	t _f	g		9	18	
Turn-On Delay Time	t _{d(on)}			48	80	ns
Rise Time	t _r	$V_{DD} = -15 \text{ V}, R_{L} = 1.5 \Omega$		92	160	1
Turn-Off DelayTime	$t_{d(off)}$ $I_D \cong -10 \text{ A}, V_{GEN} = -4.5 \text{ V}, R_g = 1 \Omega$			34	60	1
Fall Time	t _f			19	35	
Drain-Source Body Diode Characteris				<u> </u>		
Continous Source-Drain Diode Current I _S		T _C = 25 °C			- 4.1	
Pulse Diode Forward Current	I _{SM}				- 60	Α
Body Diode Voltage	V _{SD}	I _S = - 3 A, V _{GS} = 0 V		- 0.75	- 1.2	V
Body Diode Reverse Recovery Time	t _{rr}	3 / 65		27	45	ns
Body Diode Reverse Recovery Charge Q _{rr}		10 A 31/4/ 400 A / - T 05 00		16	27	nC
Reverse Recovery Fall Time	t _a	$I_F = -10 \text{ A}, \text{ dI/dt} = 100 \text{ A/}\mu\text{s}, T_J = 25 ^{\circ}\text{C}$		12		
Reverse Recovery Rise Time	t _b			15		ns

Notes:

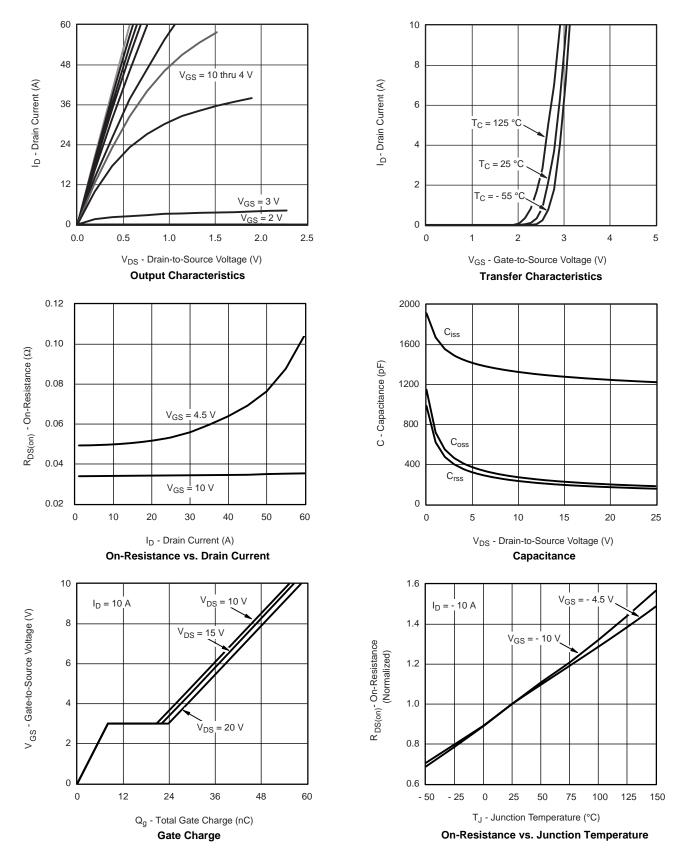
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

a. Pulse test; pulse width $\leq 300~\mu s,$ duty cycle $\leq 2~\%.$

b. Guaranteed by design, not subject to production testing.

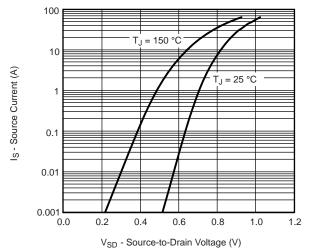


TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

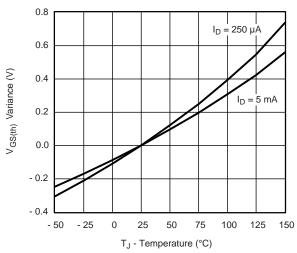




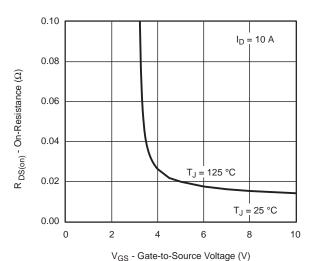
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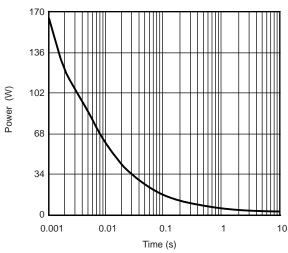
Source-Drain Diode Forward Voltage



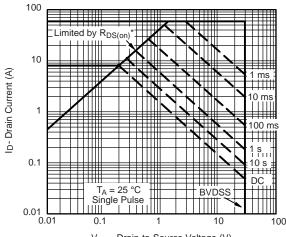
Threshold Voltage



On-Resistance vs. Gate-to-Source Voltage



Single Pulse Power, Junction-to-Ambient

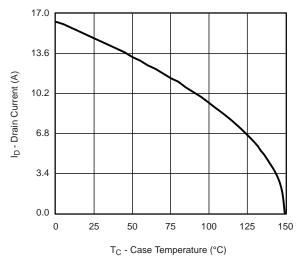


 V_{DS} - Drain-to-Source Voltage (V) * V_{GS} > minimum V_{GS} at which $R_{DS(on)}$ is specified

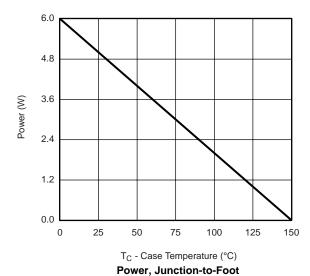
Safe Operating Area

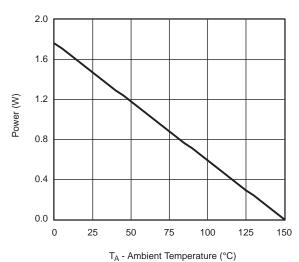


MOSFET TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



Current Derating*



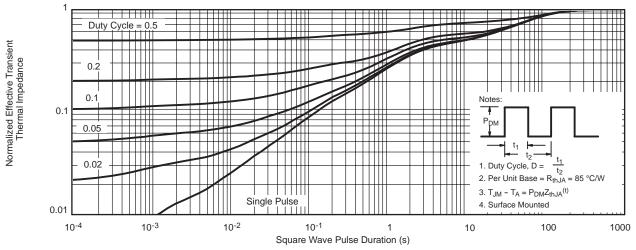


Power Derating, Junction-to-Ambient

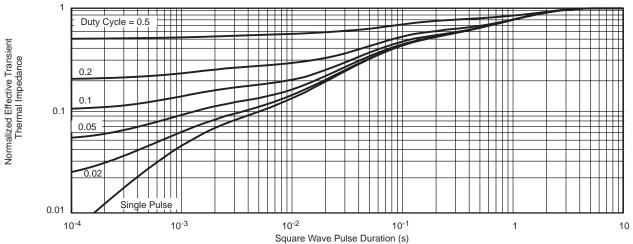
^{*} The power dissipation P_D is based on $T_{J(max)}$ = 150 °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package



TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



Normalized Thermal Transient Impedance, Junction-to-Ambient



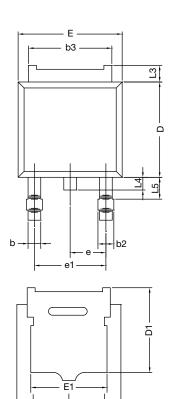
Normalized Thermal Transient Impedance, Junction-to-Foot

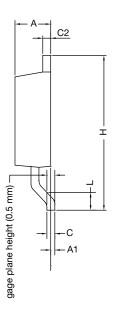
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TO-252AA CASE OUTLINE





	MILLIMETERS		INC	HES	
DIM.	MIN.	MAX.	MIN.	MAX.	
А	2.18	2.38	0.086	0.094	
A1	-	0.127	-	0.005	
b	0.64	0.88	0.025	0.035	
b2	0.76	1.14	0.030	0.045	
b3	4.95	5.46	0.195	0.215	
С	0.46	0.61	0.018	0.024	
C2	0.46	0.89	0.018	0.035	
D	5.97	6.22	0.235	0.245	
D1	5.21	-	0.205	-	
E	6.35	6.73	0.250	0.265	
E1	4.32	-	0.170	-	
Н	9.40	10.41	0.370	0.410	
е	2.28	BSC	0.090	BSC	
e1	4.56	4.56 BSC 0.180 BSC		BSC	
L	1.40	1.78	0.055	0.070	
L3	0.89	1.27	0.035	0.050	
L4	-	1.02	-	0.040	
L5	1.14	1.52	0.045	0.060	
ECN: X12-0247-Rev. M. 24-Dec-12					

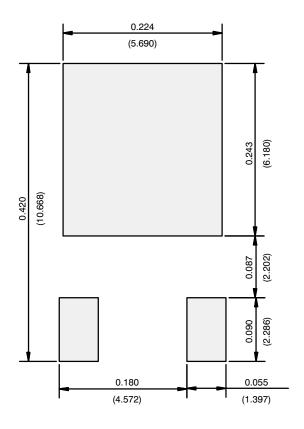
ECN: X12-0247-Rev. M, 24-Dec-12 DWG: 5347

Note

• Dimension L3 is for reference only.



RECOMMENDED MINIMUM PADS FOR DPAK (TO-252)



Recommended Minimum Pads Dimensions in Inches/(mm)



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